

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/08/2022

Details for "OPA348AIDR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA348AIDR	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	D 8	3.91x4.9x1.58	101.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.030441	100	1000000	0.029927	299
Sub-Total			0.030441	100	1000000	0.029927	299
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.05585	79.999427	799994	0.054907	549
Thermoplastics	Epoxy	85954-11-6	0.013963	20.000573	200006	0.013727	137
Sub-Total			0.069813	100	1000000	0.068634	686
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	37.624655	97.701	977010	36.989258	369893
Copper and Its Alloys	Iron	7439-89-6	0.824114	2.14	21400	0.810197	8102
Copper and Its Alloys	Phosphorus	7723-14-0	0.012708	0.032999	330	0.012493	125
Zinc and Its Alloys	Zinc	7440-66-6	0.048523	0.126001	1260	0.047704	477
Sub-Total			38.51	100	1000000	37.859651	378597
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.864352	95.12	951200	1.832867	18329
Precious Metals	Gold	7440-57-5	0.015288	0.78	7800	0.01503	150
Precious Metals	Palladium	7440-05-3	0.08036	4.1	41000	0.079003	790
Sub-Total			1.96	100	1000000	1.9269	19269
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	53.60876	87.999999	880000	52.703427	527034
Other Plastics and Rubber	Carbon Black	1333-86-4	0.182757	0.3	3000	0.179671	1797
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.335055	0.55	5500	0.329397	3294
Thermoplastics	Epoxy	85954-11-6	6.792474	11.150001	111500	6.677764	66778
Sub-Total			60.919046	100	1000000	59.890258	598903
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.228488	100	1000000	0.224629	2246
Sub-Total			0.228488	100	1000000	0.224629	2246
Total			101.717788			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.